

QF3168

No Clean Liquid Flux



Product Description

QF3168 is a no-clean RMA flux, designed to offer excellent solderability on higher density packaging in lead free soldering. It provides uniform matte solder surface and eliminates post-cleaning process. The residue left behind is non-tacky, non-corrosive and non-conductive, with superior electrical insulation. It is made to work well with both foam and spraying fluxers.

Application

QF3168 is specially formulated for spraying as well as foaming and dipping process. Recommended onboard preheat temperature is 90 – 110 °C.

Residue Removal

Since the residues are minimal and non-corrosive, removal is usually not required. If cleaning is required, the flux residue could be removed by any solvent or aqueous flux cleaner available in the market.

Recommended Solvent

Asahi's complementary Solvent #2000. Solvent can be stored for about 2 year under normal storage conditions of 25°C.

Health and Safety

Observe standard precautions for handling and use, such as well-ventilated areas and avoidance of prolonged or repeated contact with the skin. For more information, please refer to the Material Safety Data Sheet.

Storage

Under proper storage condition, QF3168 can be stored for up to 6 months. QF3168 is flammable. Keep away from all sources of heat, sparks, flame and sunlight.

Packaging

Available in 18kg/carboy.

Specification

Item	Result
State	Clear and transparent liquid
Colour	Pale yellow
Specific Gravity @ 25°C	0.798 +/- 0.005
JIS Z 3197 8.2.2	
Non-volatile Solid Content (110°C, 1hr)	6.8 +/- 0.5 wt%
IPC-TM-650 2.3.34	
JIS Z 3197 8.1.3	
Halide Content	0.06 +/- 0.01 wt%
JIS Z 3197 8.1.4.2.1	
Acid Value Test	19.0 +/- 1 mg KOH/g flux
IPC-TM-650 2.3.13	
JIS Z 3197 8.1.4.1	
Water Extract Resistivity	> 1 x 10 ⁵ Ω-cm
JIS Z 3197 8.1.1	
Surface Insulation Resistance (85°C, 85%RH, 168hrs)	> 1 x 10 ⁸ Ω, Pass
IPC-TM-650 2.6.3.3	
JIS Z 3197 8.5.3	> 1 x 10 ¹¹ Ω, Pass
Electromigration (85°C, 88.5%RH, 596hrs)	Pass
IPC-TM-650 2.6.14.1	
Copper Corrosion Test	Pass
IPC-TM-650 2.6.15	
JIS Z 3197 8.4.1	
Copper Mirror Test	Classified as "M", Pass
IPC-TM-650 2.3.32	
JIS Z 3197 8.4.2	
Flux Activity Classification	ROM1
IPC J-STD-004	
Spread Factor	> 75% (SCS7)
JIS Z 3197 8.3.1.1	
Residue Dryness Test	Dry
IPC-TM-650 2.4.47	
JIS Z 3197 8.5.1	
Surface Finish	Matte

DISCLAIMER OF LIABILITY

"All statements, information and recommendations contained in this catalog are based on data and test results which we consider, to the best of our knowledge and belief, to be reliable and informative to the users but the accuracy and completeness thereof is not guaranteed. No warranty, expressed or implied, statutory or otherwise, is given regarding the use of the information and products contained in this catalog since the conditions and suitability for use, handlings, storage or possession of the products are determined by the users and are therefore beyond our control. We shall not be liable in respect of any liabilities, losses (including consequential losses), damages, proceedings, costs, claims or injuries whatsoever sustained or suffered by the users (including any third parties) in connection with the use of the information, recommendation and the products contained in this catalog."

Singapore Asahi Chemical and Solder Industries Pte Ltd

47 Pandan Road Singapore 609288

Tel: +65 6262-1616 Fax: +65 6261-6311

Website: <http://www.asahisolder.com> Email: enquiry@sinasahi.com.sg